

Kester® NP505-HR

High-Reliability, Zero-Halogen, Lead-Free, No-Clean Solder Paste

A Paste for High Reliability Applications

Kester NP505-HR Solder Paste is a high reliability, zero-halogen, lead-free, no-clean solder paste. NP505-HR is specifically designed for challenging applications such as automotive and aerospace where superior SIR performance is required. NP505-HR provides very reliable post-reflow residues and passes the most challenging industry SIR conditions. NP505-HR is available in both SAC305 and the leading high performance Innolot alloy.



Key Features

- Zero-Halogen*
- Reliable post reflow residues passing even the harshest SIR testing
- Reflowable in both air and nitrogen
- Consistent print performance to 0.55AR (SAC305) and 0.57AR (Innolot)
- Low QFN/BGA voiding
- Excellent solderability across wide variety of profiles
- Compatible with most conformal coating materials
- Stable paste properties: 12-month shelf life for SAC305 and 6-month shelf life for Innolot



*Zero-halogen is defined as no halogen intentionally added to the formulation.



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PERFORMANCE SUMMARY

| PROCESS | PERFORMANCE ATTRIBUTE | NP505-HR WITH INNOLOT CAPABILITY |
|----------|---------------------------------|--|
| Printing | Print Definition | Consistent fine feature print volumes, reaching area ratio of 0.57 with standard print set-up. Able to reduce AR with advanced printing technology |
| | Print Durability (Stencil Life) | No significant paste degradation after 6 hours of printing |
| | Print Relax & Recovery | 2 hours relax/recovery remains consistent across full range of viscosity |
| | Print Temperature Window | Consistent printing performance at the temperature of 22-30 °C/71.6-86 °F and the relative humidity of 30-65% RH |
| | Print Speed Range | Consistent printing performance from speeds of 1-6 in/s (25-150 mm/s). Slower speeds are beneficial for area ratios at or below 0.55 |
| Reflow | Reflow Process Window | Consistent solderability across all profiles – short, medium or long soak in both air and nitrogen |
| | Void behavior | Minimum voiding observed across variety of reflow profiles |
| | Hot/Cold Slump Performance | Meets requirements of IPC J-STD-005B |
| | Flux Residue Appearance | Light clear residues |
| | ICT Probability | Consistent hard probable surface, shatter-type residue |



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Kester is a product brand of MacDermid Alpha Electronics Solutions.

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